
APPROXIMATE MODELLING PROCESSES FOR RAPID ANALYSIS AND DESIGN

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Overview

What is modelling?

How can approximate modelling methods be used to understand thermal behaviour in electronics applications

Modelling procedures: as applied to heat sinks

Other potential applications



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Modelling Alternatives

Experimental Methods

- prototype testing
- empirically-based correlations

Numerical Methods

- approximate the governing equations over a finite, discretized domain

Analytical Methods

- closed form solutions
- approximate methods



Why Use Approximate Methods?

Fast, accurate and easy to use

Minimal hardware requirements

Ideal for preliminary design studies

- material selection
- component selection and placement
- trade-off studies

Optimization studies

Concurrent design



Perceived Limitations

Limited range of applications

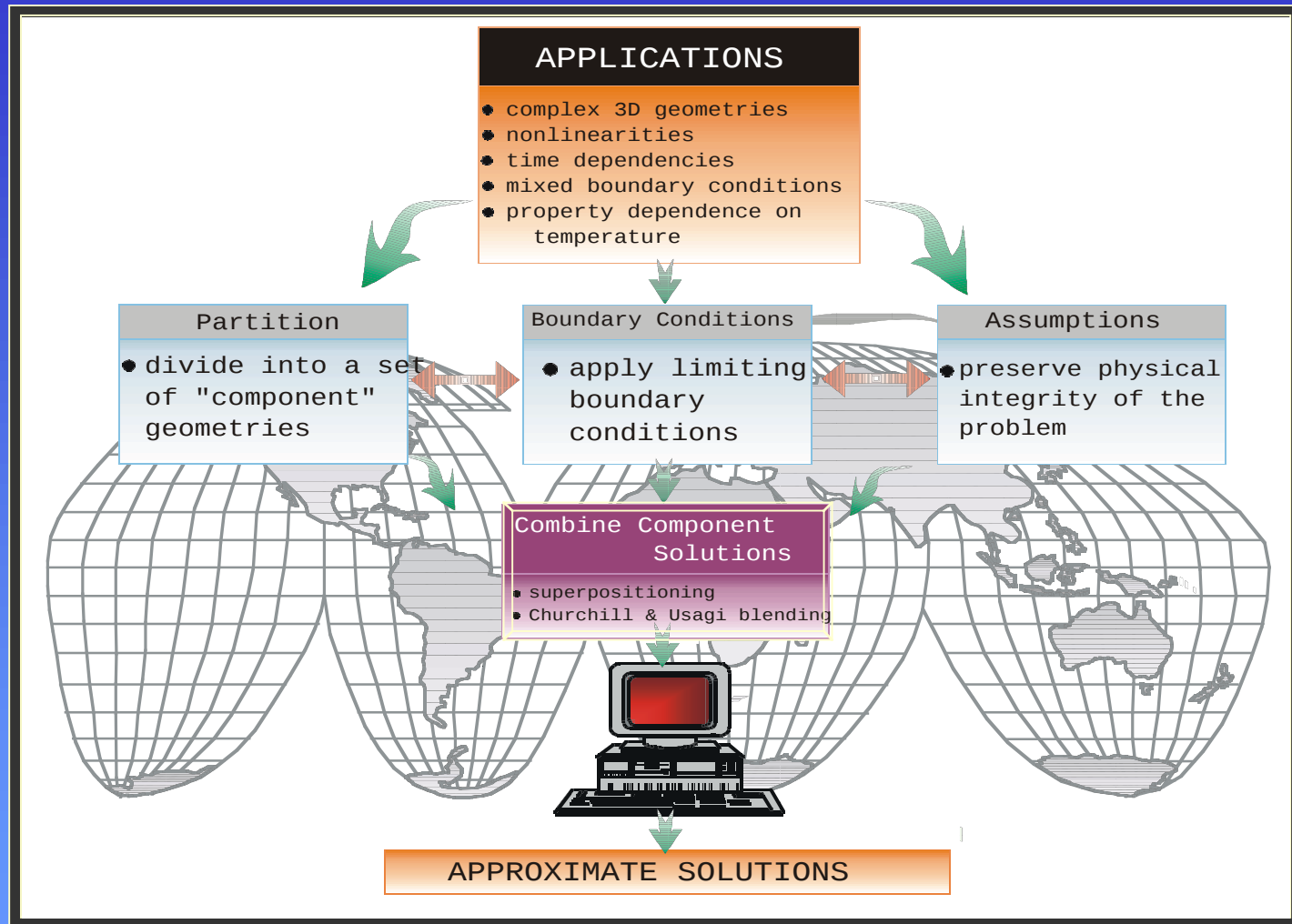
Cannot be used for complex geometries

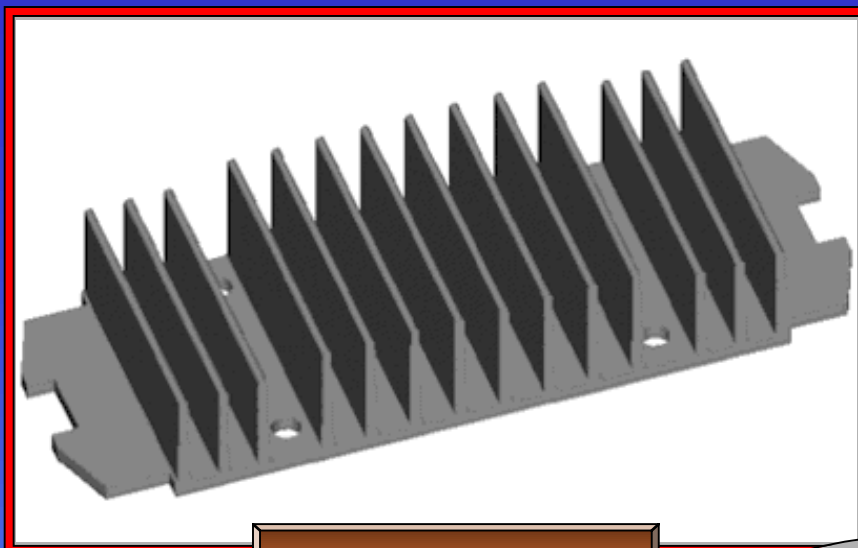
Cannot be used with mixed or non-uniform boundary conditions

Simplifying assumptions provide inaccurate solutions

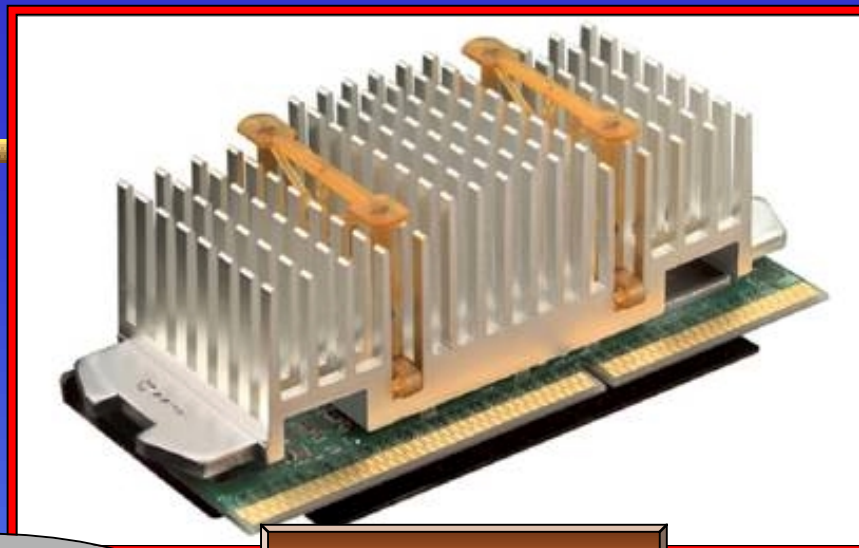


Modelling Approach





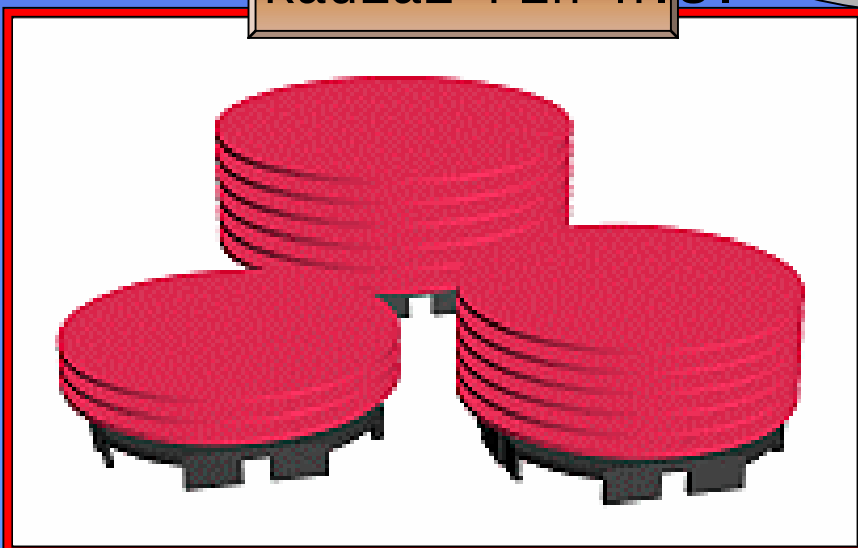
PlateFin H.S.



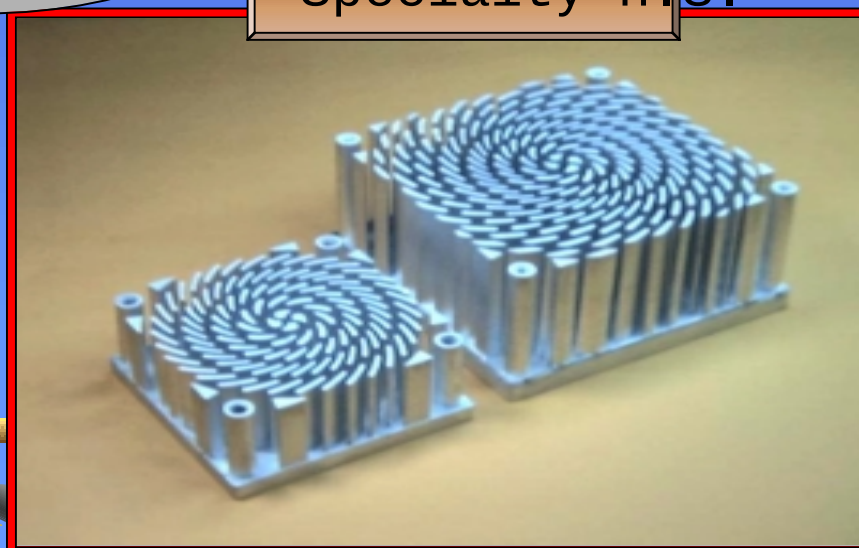
Pin Fin H.S.

Heat Sink Alternatives

Radial Fin H.S.



Specialty H.S.

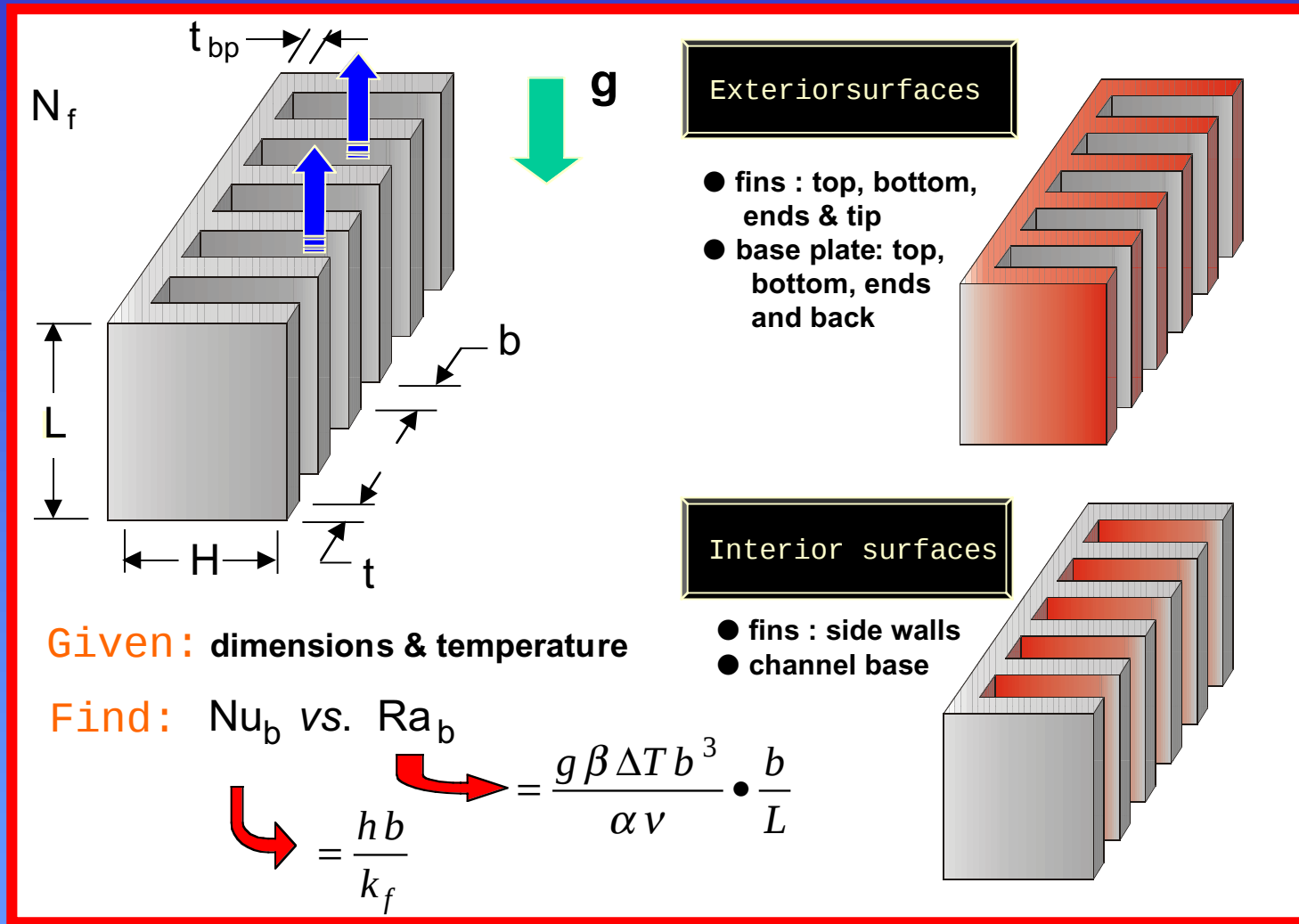


Heat Sink Model

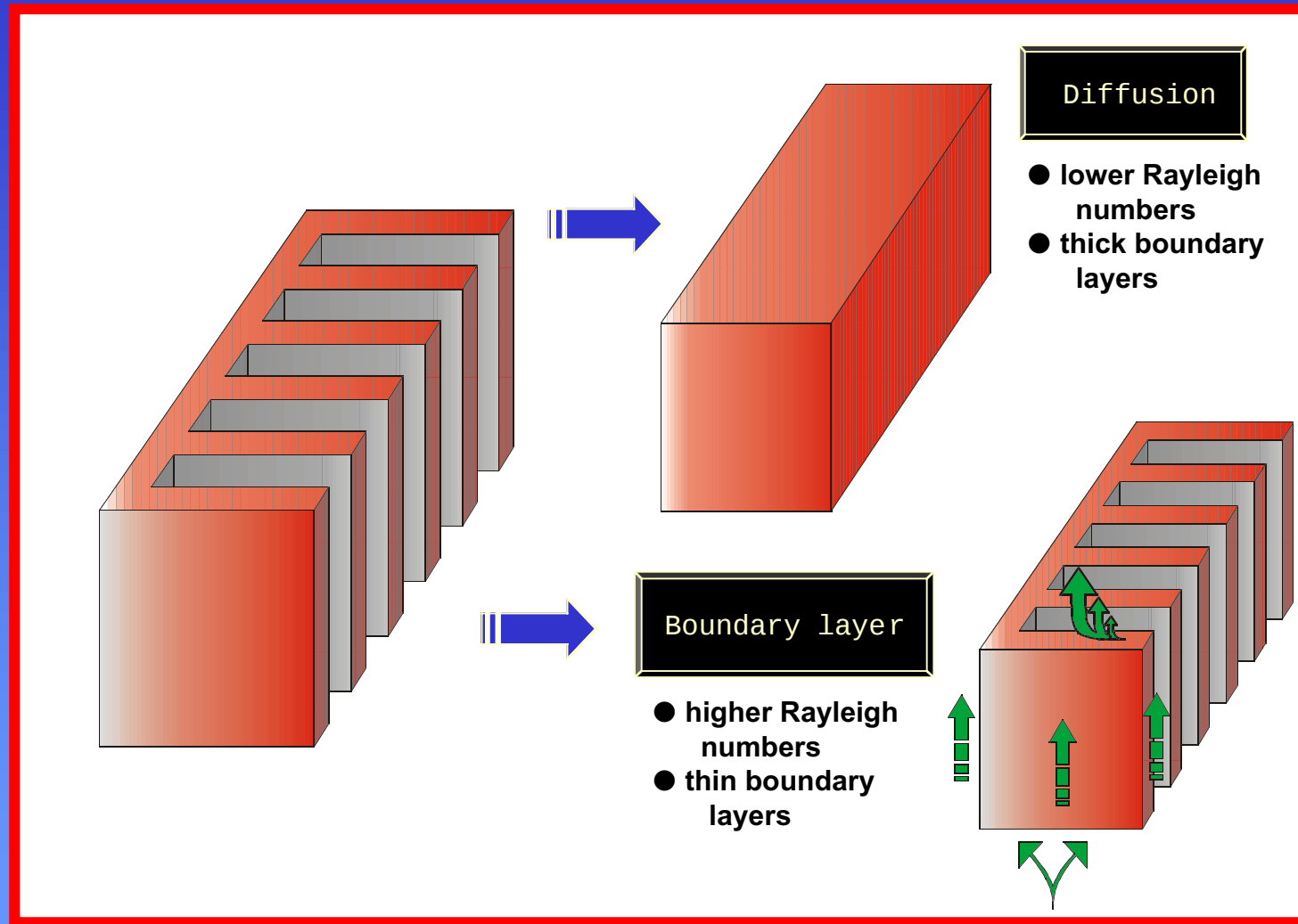
- Plate fin heat sink
- Natural convection
- Vertical orientation
- Isothermal
- Steady state
- Working fluid is air



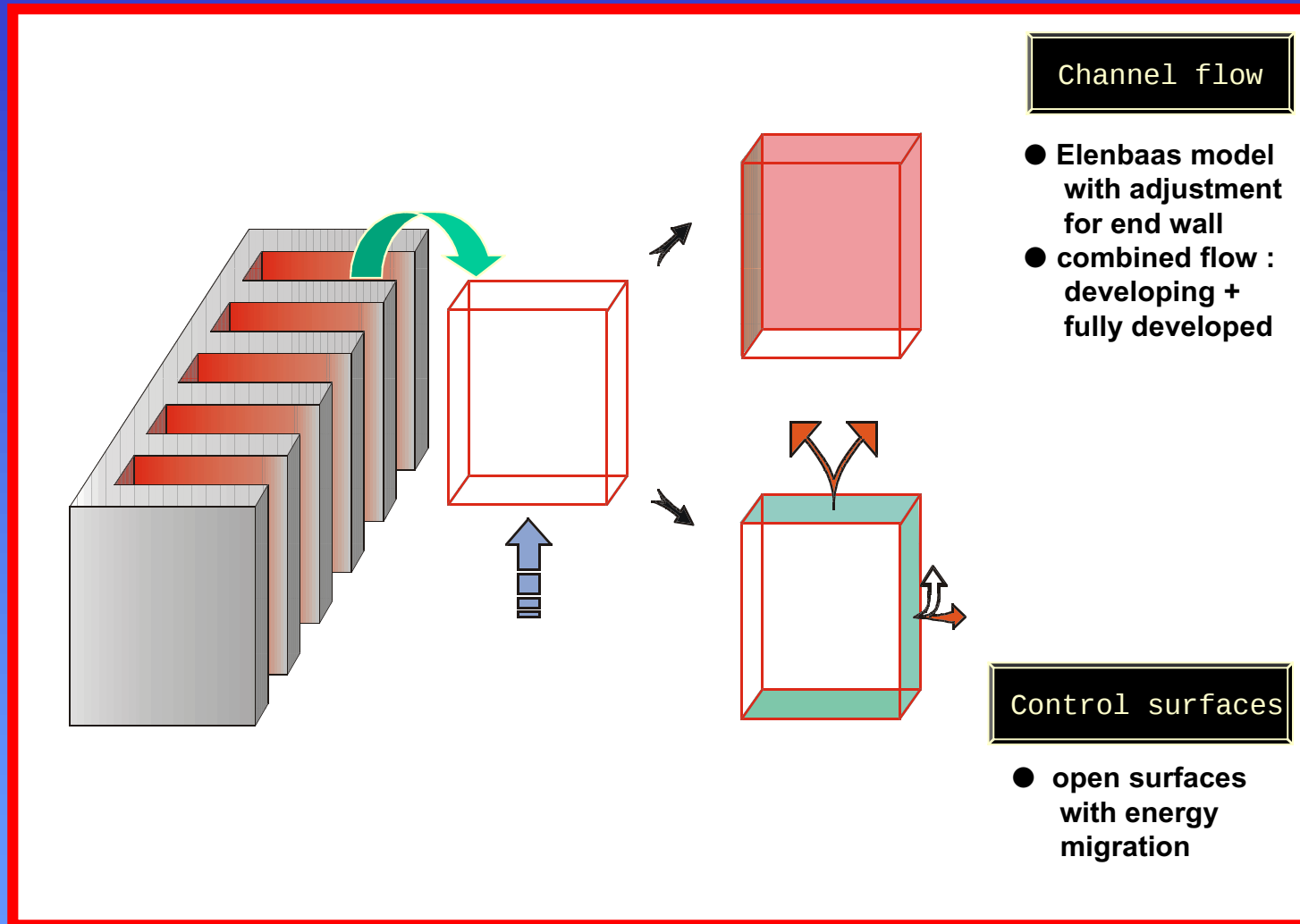
Modelling Procedure



Exterior Surfaces



Interior Surfaces

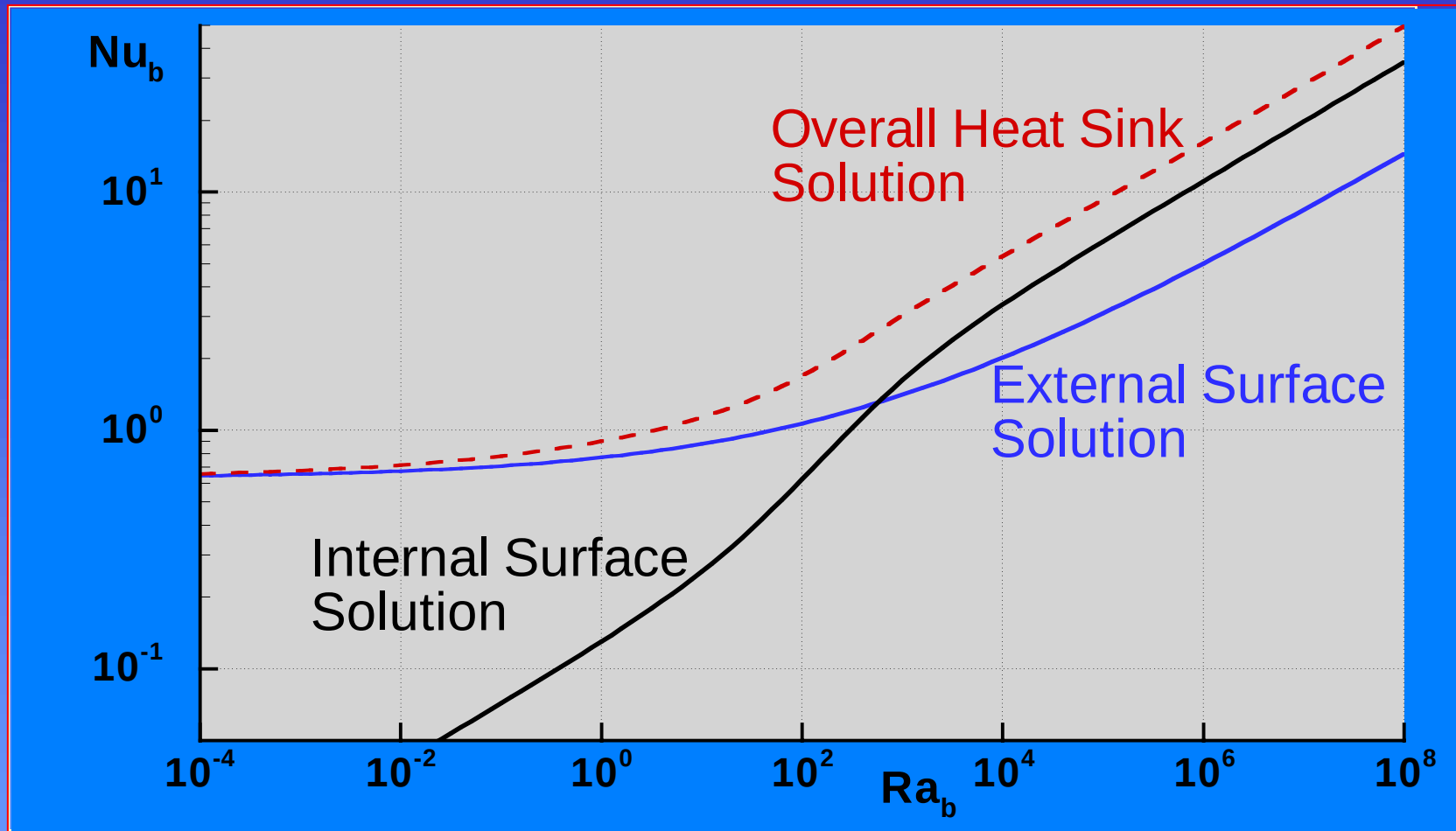


Comprehensive Model

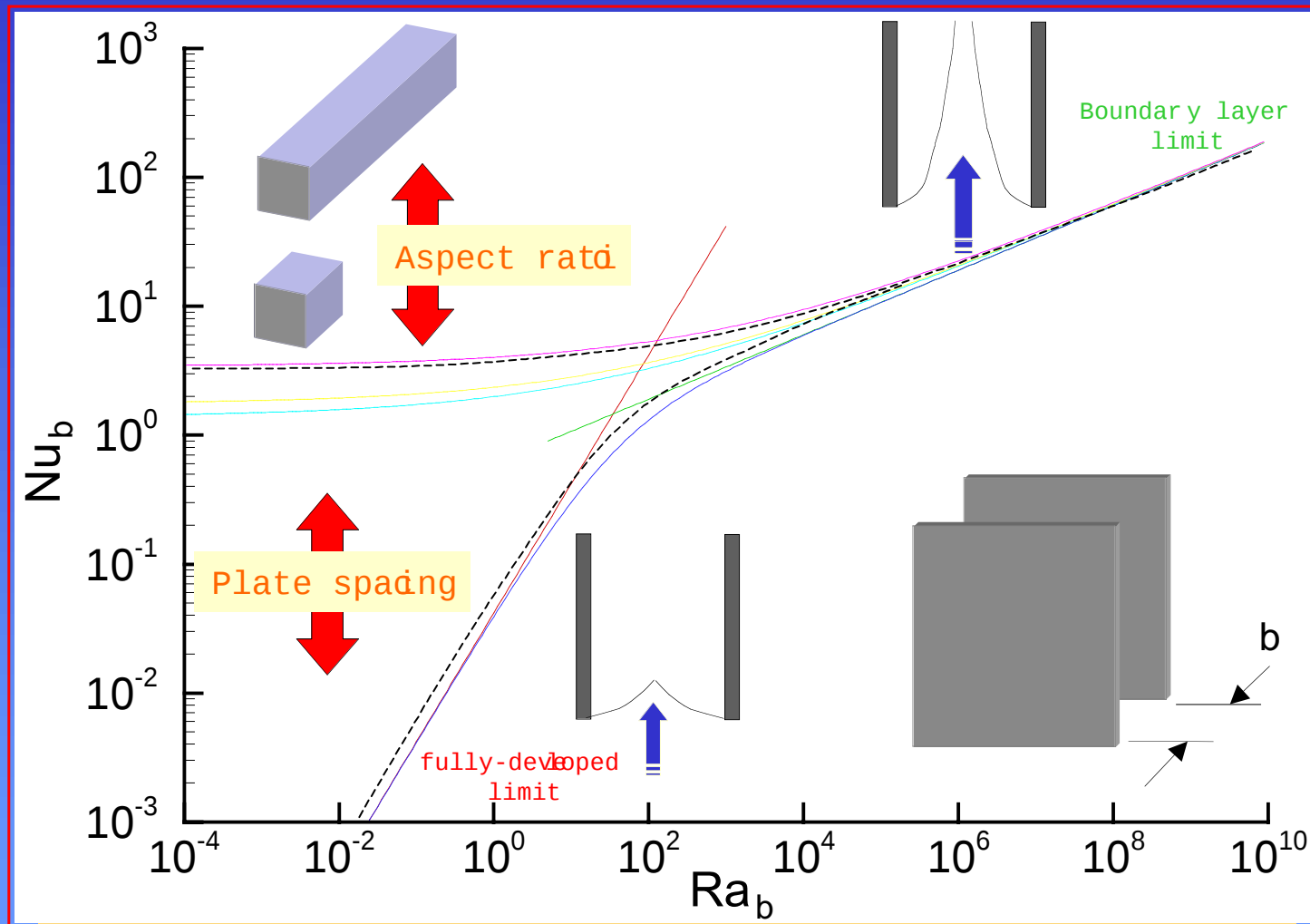
$$Nu = \underbrace{Nu_0}_{\text{diffusion}} + \frac{1}{\frac{1}{\underbrace{Nu_2}_{\text{channel flow}}} + \frac{1}{\underbrace{Nu_3 + Nu_4}_{\text{external boundary layer flow}}}} + \underbrace{Nu_1}_{\text{external boundary layer flow}}$$

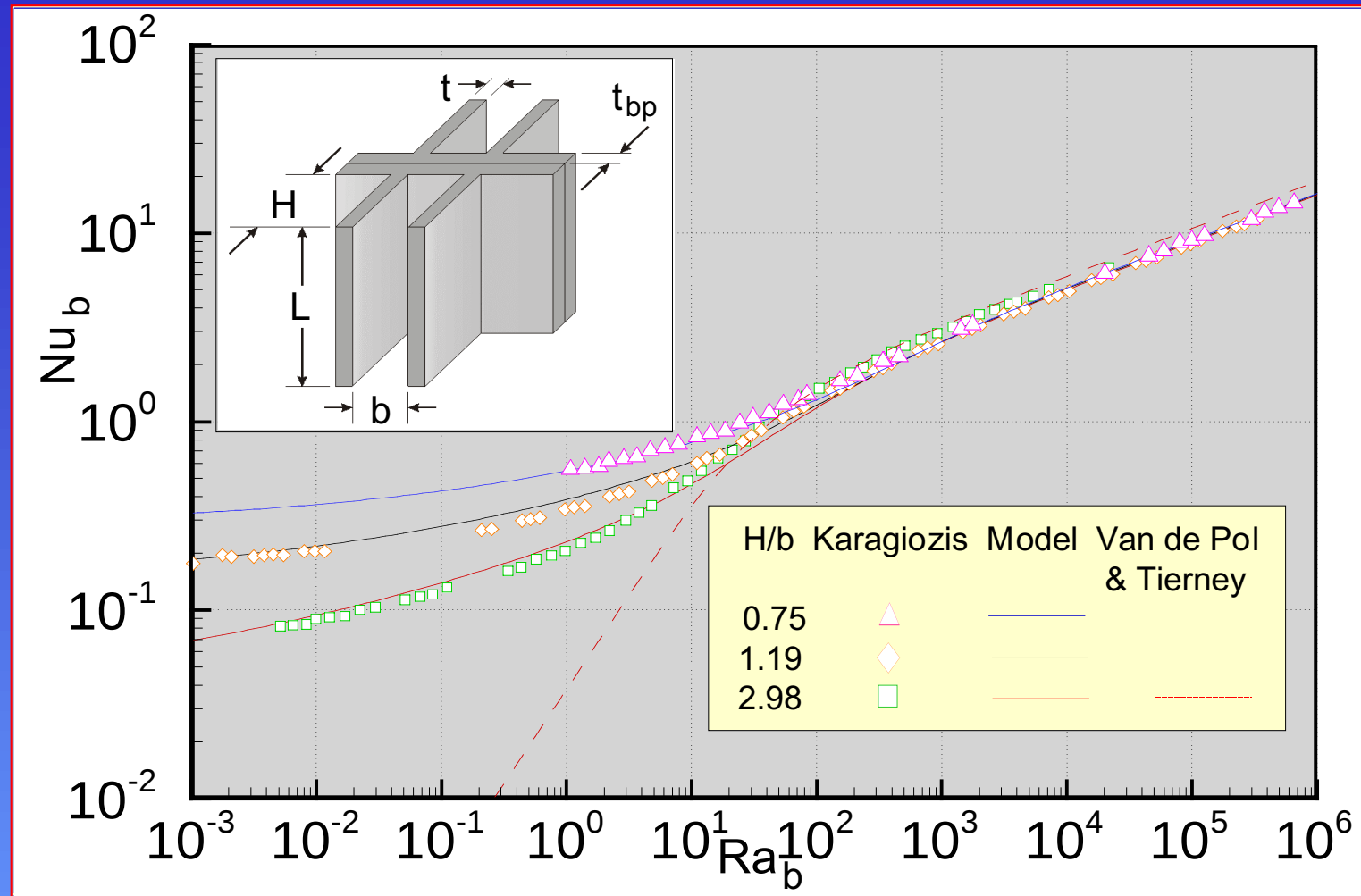


Total Composite Solution



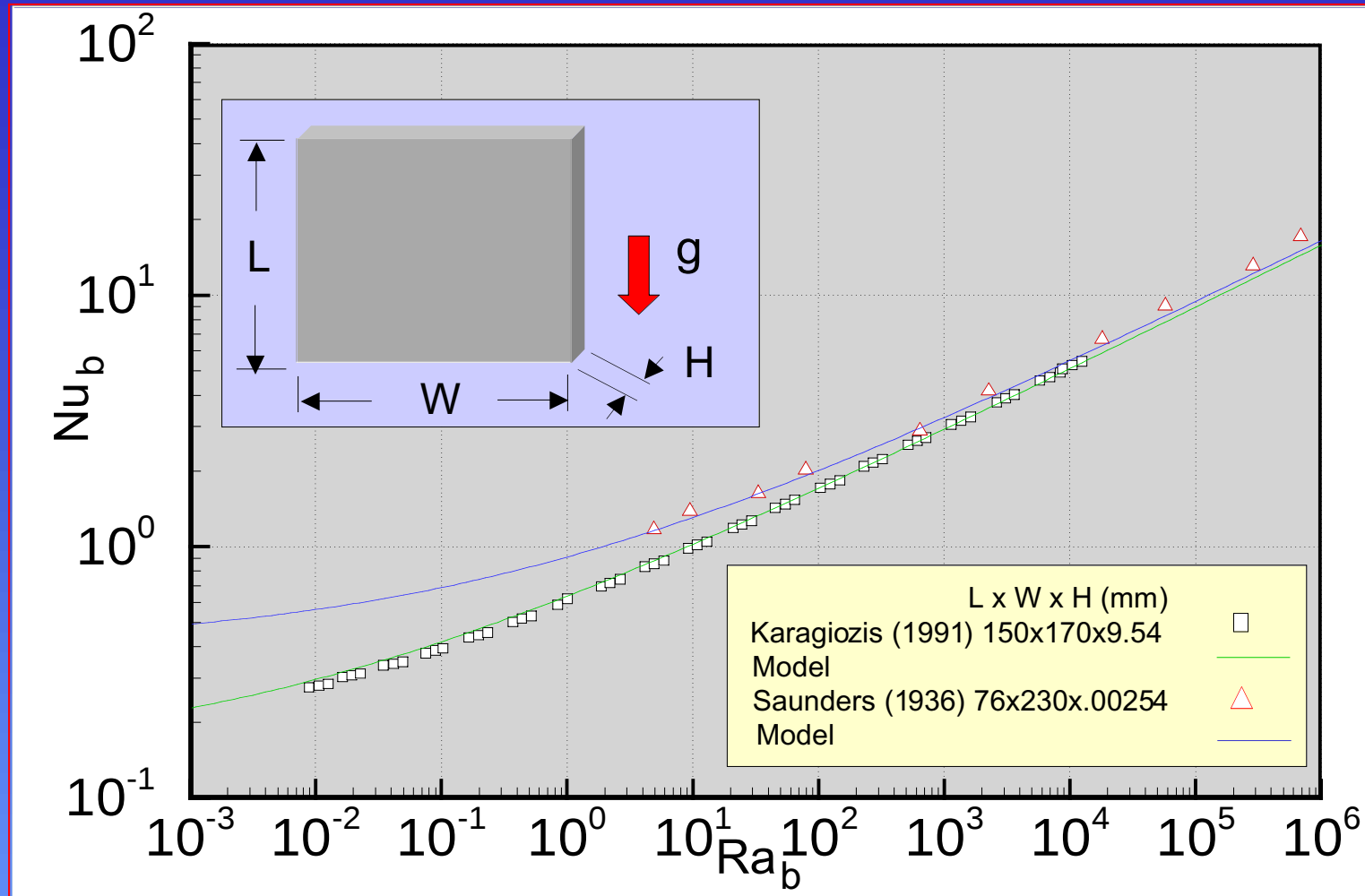
Modelling Domain





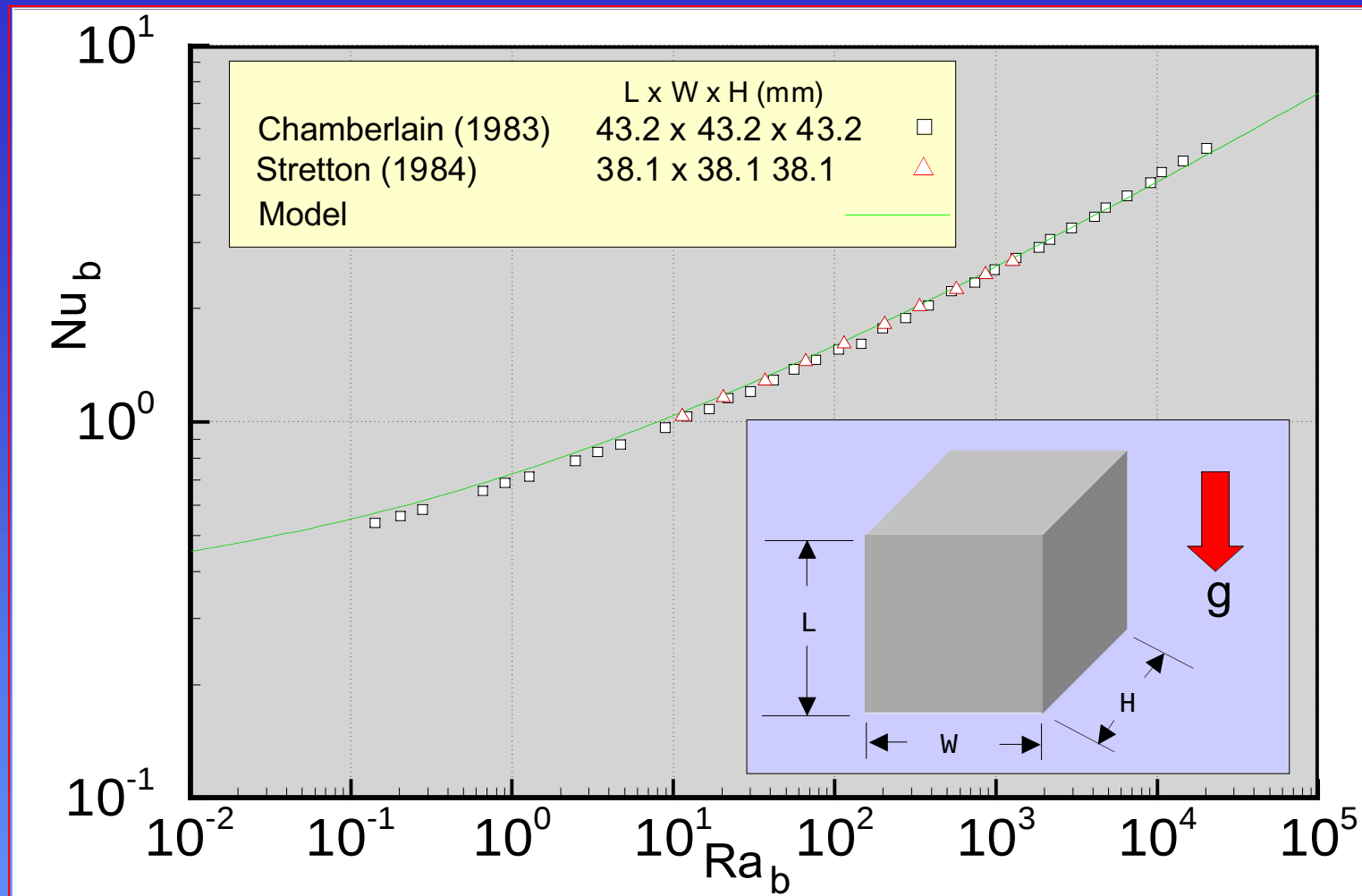
$$Nu = Nu_0 + \left\{ Nu_2^{-2} + [Nu_3 + Nu_4]^{-2} \right\}^{-1/2} + Nu_1$$





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How Do We Use These Results?

dimensionless heat
transfer coefficient

dimensionless flow
parameter

$$Nu_b = \frac{hb}{k_f} = \frac{Q}{\Delta T \cdot A} \cdot \frac{b}{k_f} \propto \frac{g\beta\Delta Tb^3}{\alpha\nu} \cdot \frac{b}{L} = Ra_b$$

If max. ΔT changes $\Rightarrow$ what is the max. Q dissipated

For a given $Q \Rightarrow$ what is the max. ΔT of the heat sink
or the package junction

How do changes in geometry affect $\Rightarrow \Delta T$ and Q



Future Work

Goal: Develop a comprehensive model to find the best heat sink design given a limited set of design constraints

Physical Design

- ¥ heat sink type
- ¥ material
- ¥ weight
- ¥ dimensions
- ¥ surface finish

Thermal

- ¥ maximum volume
- ¥ boundary conditions
- ¥ max. allowable temp.
- ¥ orientation
- ¥ flow mechanism

Cost

- ¥ labour
- ¥ manufacturing
- ¥ material

Standards

- ¥ noise
- ¥ exposure to touch



Other Examples of Approximate Models

<i>Applications</i>	<i>Asymptotic Limits</i>	
<i>Heat & Mass Transfer</i>		
<i>1 Boundary layer flow</i>	laminar	turbulent
<i>1 Channel flow</i>	fully developed flow	boundary layer flow
<i>1 External flow</i>	diffusion	boundary layer flow
<i>1 Internal flow</i>	fully developed flow	developing flow
<i>1 Enclosures</i>	diffusion	boundary layer flow
<i>1 Transient conduction</i>	short time	steady state
<i>1 Radiation</i>	opaque	transparent
<i>1 Steady conduction at nano-scales</i>	rarefied	continuum
<i>Moving Sources</i>	stationary	fast moving
<i>Elasto-plastic contacts</i>	elastic	plastic



Summary

Approximate models offer superior speed of execution and ease of use over most conventional modelling methods

Analytical modelling can be used for a wide range of applications previously considered to be too complex



The End



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